IN THE SPECIFICATION:

Please amend paragraph [0060] as follows:

[0060] As is illustrated in Figure 6, when a metal layer 30 is deposited on the structure illustrated in Figure 5, a T-gate 50 is formed on the substrate 1. A feature is that the sides of the thickest part of the T-gate and level with the second layer 20 of radiation sensitive material are spaced away from the sides of the remaining second layer 20. Thus, there is a lateral gap ~~50~~ 35 between the metal layer 30 and the second layer 20. The lateral gap 35 is important because it allows solvent to attack the first layer 10 during lift-off which follows deposition. The presence of that gap 35 is the direct result of the negative ~~slop~~ slope of the developed second layer 20. After lift-off the metal layer 30 deposited on the second layer, the second layer 20 and the first layer 10 are removed to leave a T-gate 50 on the substrate 1 as is shown in Figure 2e.